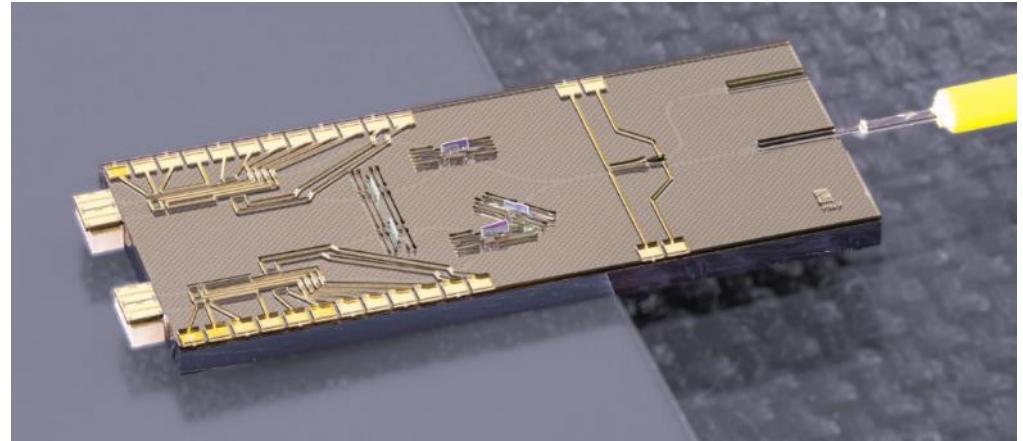

From Communications to Quantum Technology and Sensing

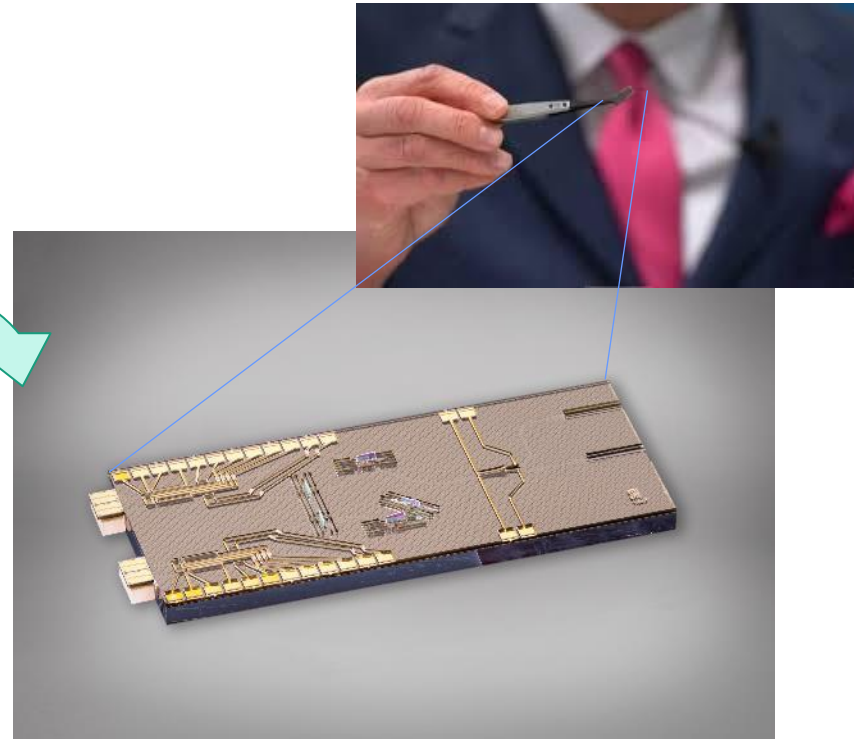
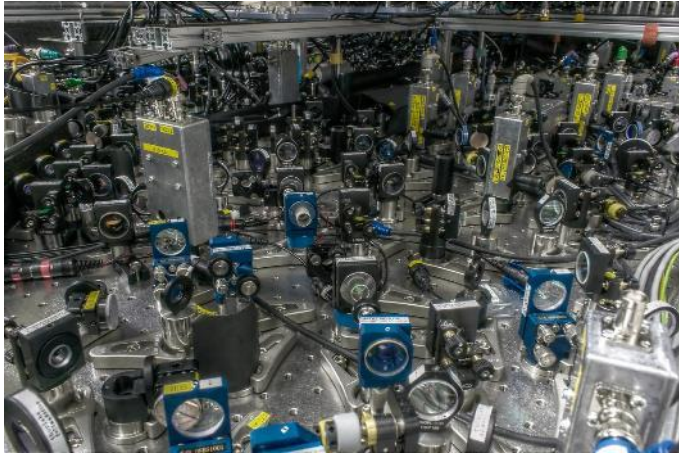
The Versatility of Hybrid Photonic Integration Technologies

Moritz Kleinert

Fraunhofer Heinrich Hertz Institute
Photonic Components Department

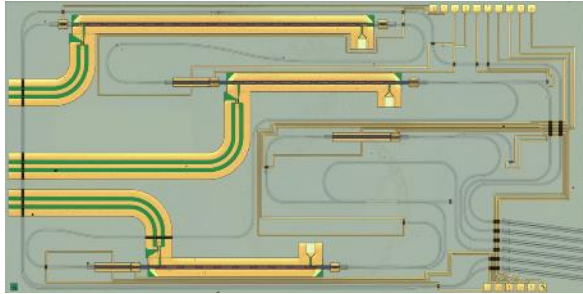


Photonic Integration



Integration of lasers, detectors, waveguides, filters, ...

Photonic Integration

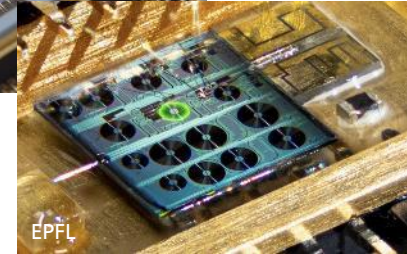
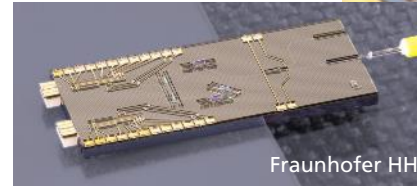
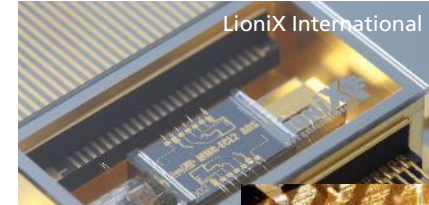


Monolithic Integration

Waveguides and actives on same die

→ Semiconductor material system, mostly InP

- + Optical sub-assembly = fabricated chip
- Limited by properties of material



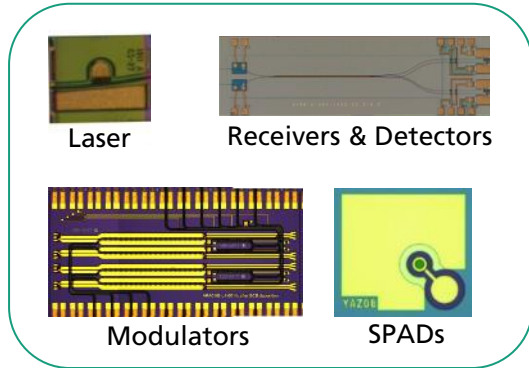
Hybrid Integration

Waveguides and actives on separate dies

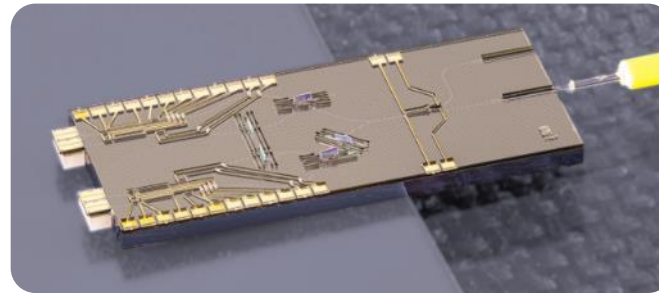
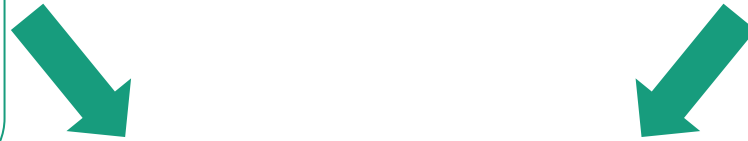
- actives: semiconductor
- passives: Silica, Si_3N_4 , polymer, TFLN, ...
- NLO: ppLN, ppKTP, ...

- Additional assembly necessary
- + Combination of optimal components and novel functionalities
- + Yield management → known good dies

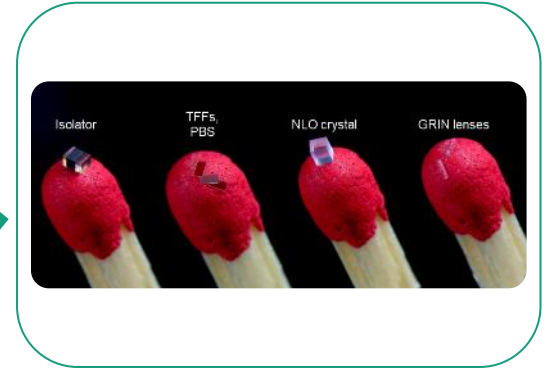
Hybrid Photonic Integration at HHI



Single components



Hybrid PIC – PolyBoard



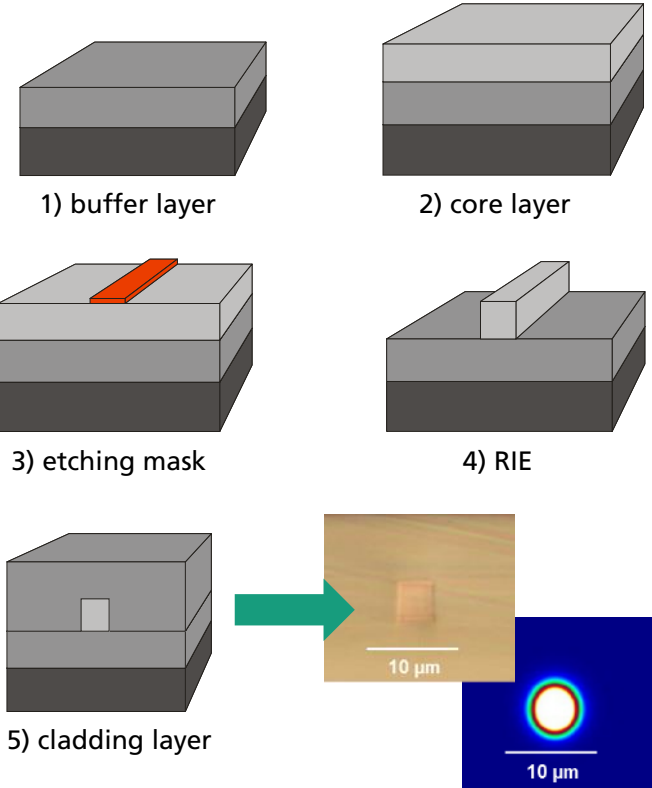
Micro-optical elements

The PolyBoard Platform

HHI's polymer-based photonic technology PolyBoard

- 4" and 6" wafer technology
→ scaling to 8" in the roadmap
- Single-mode waveguides
- Refractive index contrast between $\Delta n = 0.005$ and $\Delta n = 0.030$
- No coating / polishing required

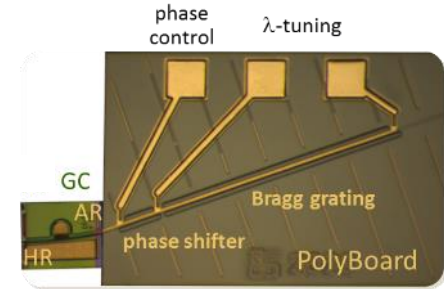
Δn	Fiber butt coupling loss	Min. bend radius	Waveguide cross section
0.005	0.1 dB	15.0 mm	7.3 μm x 7.3 μm
0.011	0.6 dB	6.0 mm	6.0 μm x 6.0 μm
0.030	1.0 dB	1.5 mm	3.2 μm x 3.2 μm



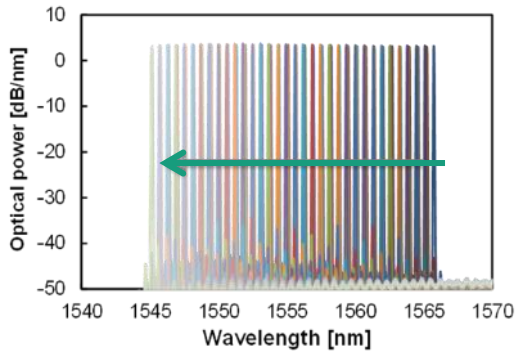
Hybrid Tunable Lasers

Flexible integrated light sources

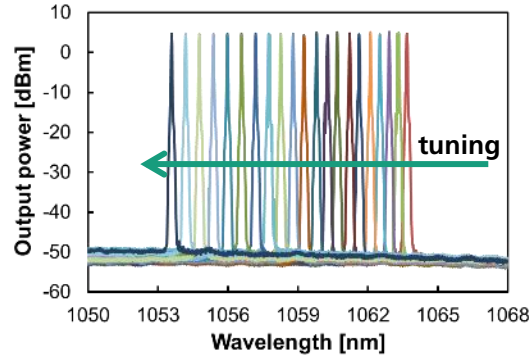
- Single photons via weak coherent pulses
- Integrated pump for non-linear optics
- Laser concept can be transferred into VIS \rightarrow gain chip material



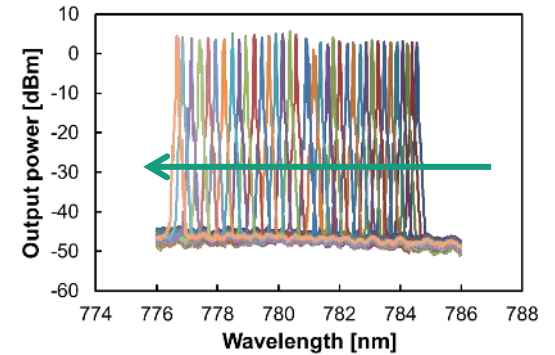
C band \rightarrow InP gain chip



1064 nm \rightarrow GaAs gain chip



785 nm \rightarrow GaAs gain chip

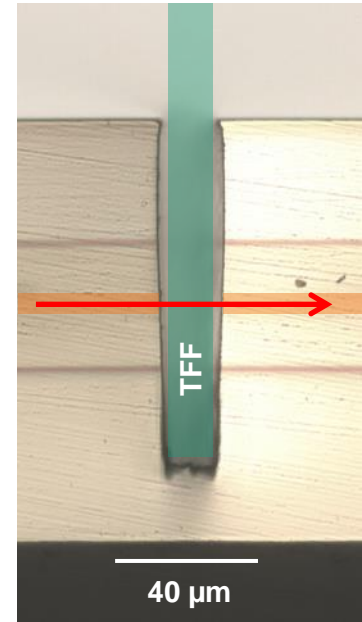
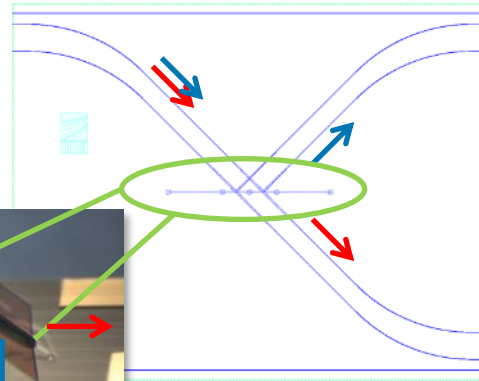
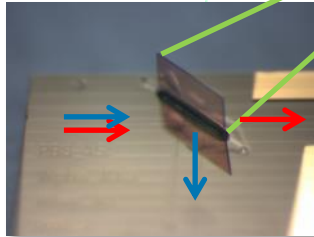
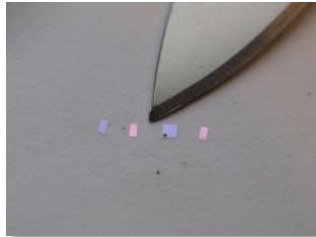
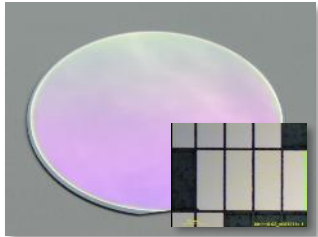


Slots & Thin Film Elements

Efficient on-chip filtering

Thin-film elements are based on dielectric layer stacks

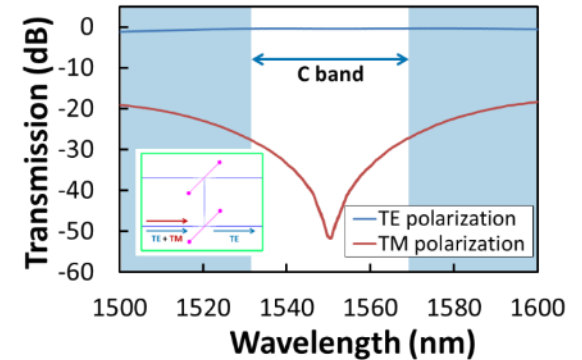
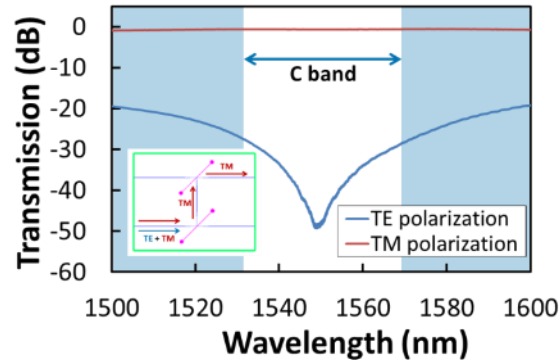
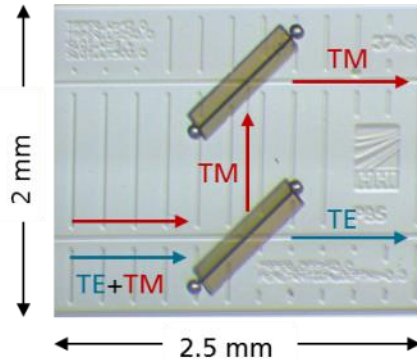
- Various efficient filter characteristics
→ wavelength, polarization etc.
- Small footprint
- Temperature-insensitive



Slots & Thin Film Elements

Example: Efficient polarization splitter

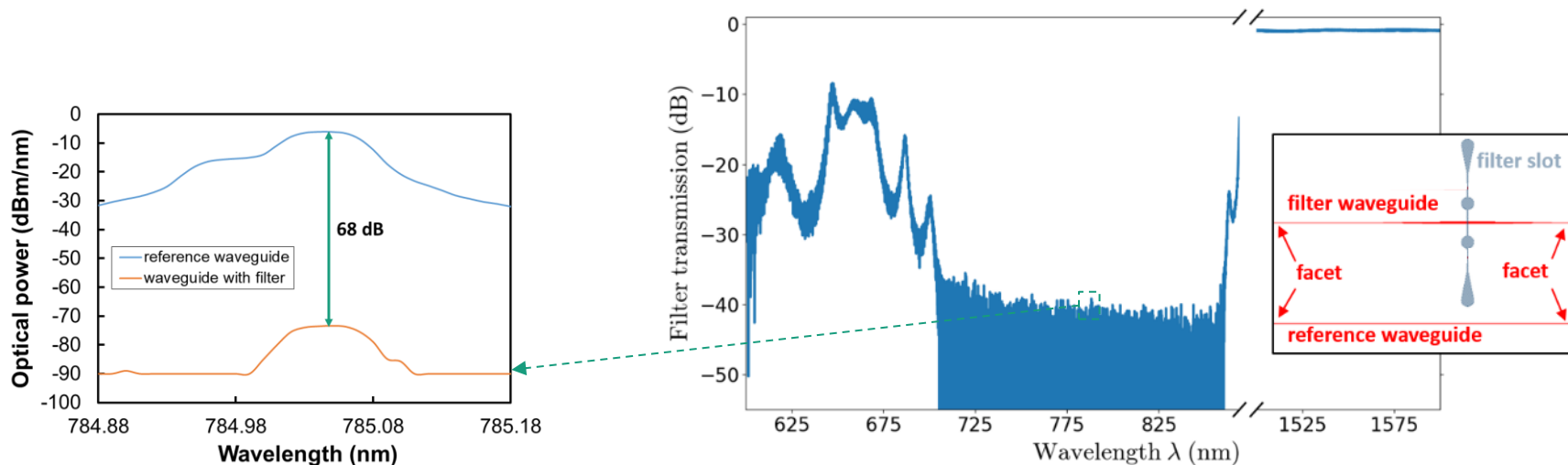
- Footprint: some mm²,
- Total insertion loss: <0.7 dB (fiber-chip-fiber)



Slots & Thin Film Elements

Example: Pump suppression filter

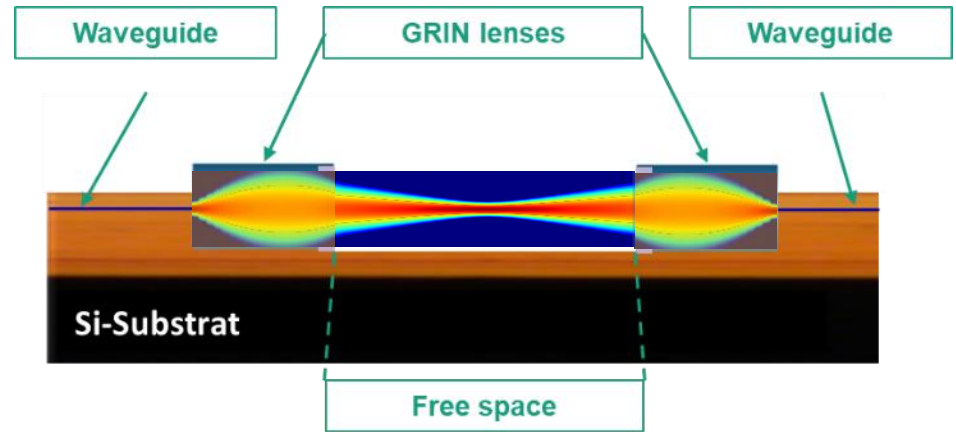
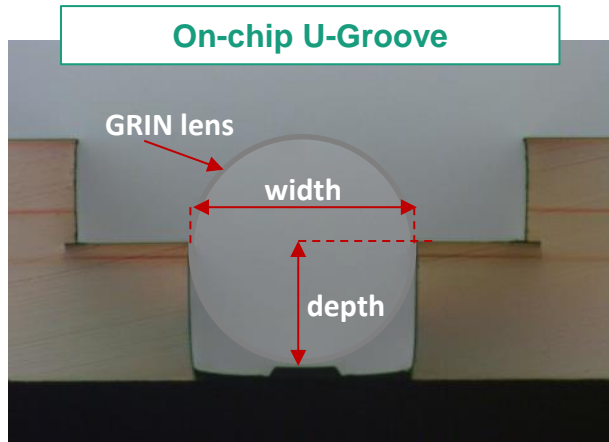
- Pass: C band / stop: around 785 nm
- 68 dB pump suppression on chip



Micro-Optical Bench

On-chip free-space sections

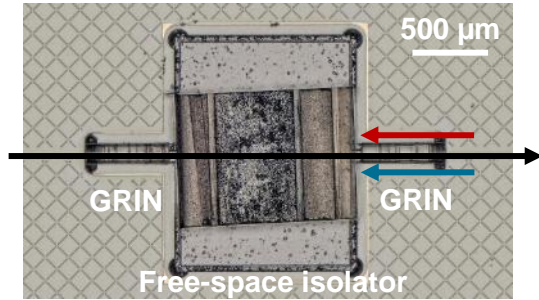
Beam collimation with GRIN lenses in on-chip U groove



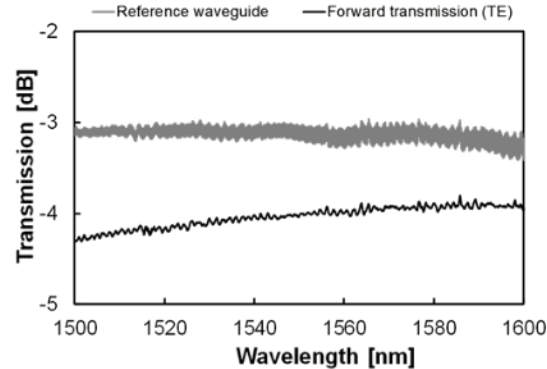
Free-space sections with lengths up to 10 mm
→ insertion of non-linear + non-reciprocal crystals

Micro-Optical Bench

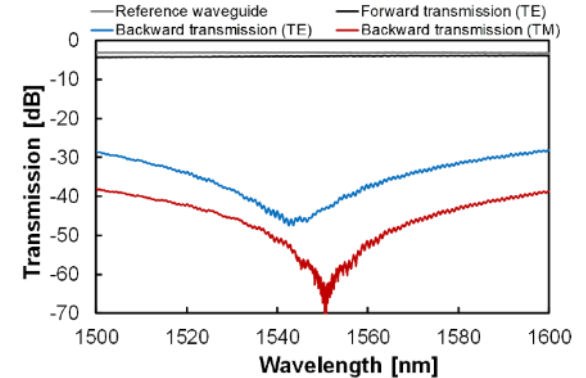
Example: Integrated optical free-space isolator



On-chip integrated free-space isolator



<1 dB on-chip loss in forward transmission

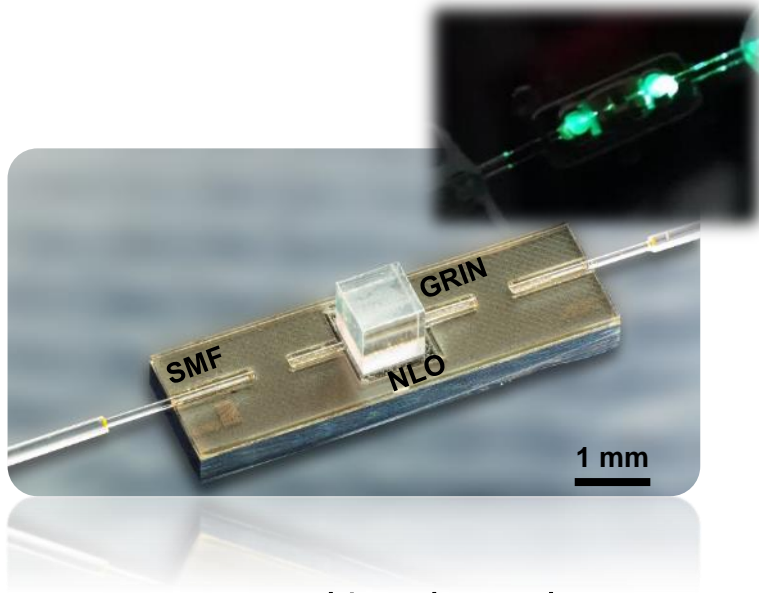


>40 dB peak isolation

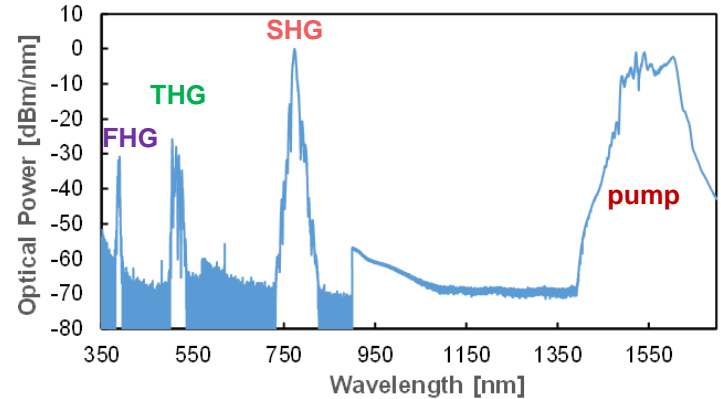
<1 dB @1550 nm // > 28 dB isolation over 100 nm bandwidth

Micro-Optical Bench

Example: Non-linear optics with bulk crystals

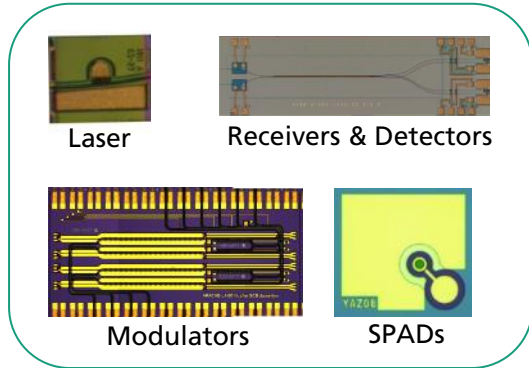


NLO crystal in PolyBoard

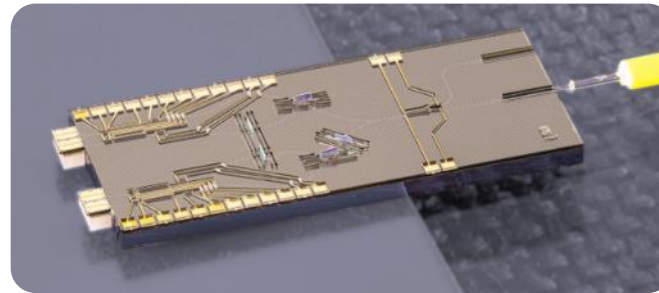


Higher harmonic generation
1550 nm \rightarrow 775 nm + 515 nm + 387 nm

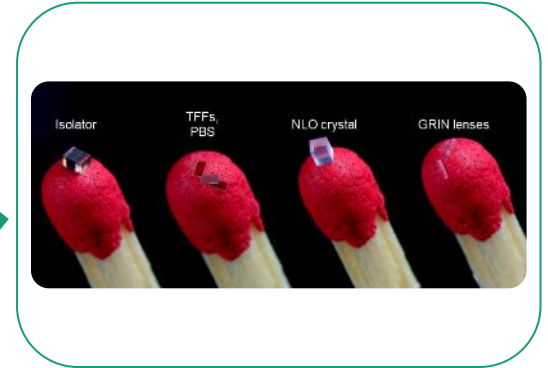
Hybrid Photonic Integration at HHI



Single components



Hybrid PIC – PolyBoard



Micro-optical elements

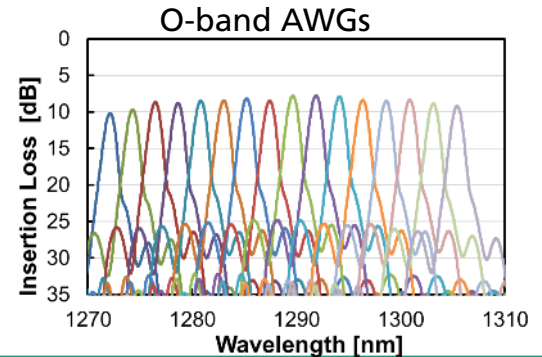
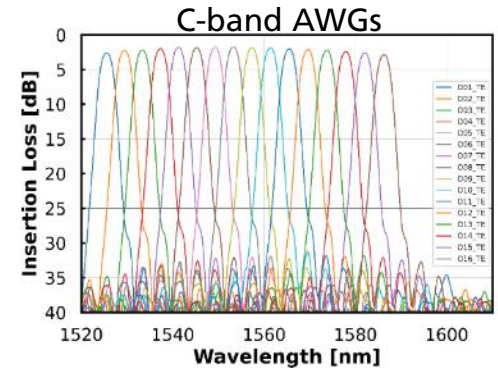
The Photonic Engine for Transceivers

PolyBoard AWGs for MUX/DEMUX

Tx & Rx AWGs on the same chip



Possibility of tuning channels w/ μ -heaters



Putting all the Building Blocks Together TRx

PolyBoard-based hybrid PIC for WDM Transceivers

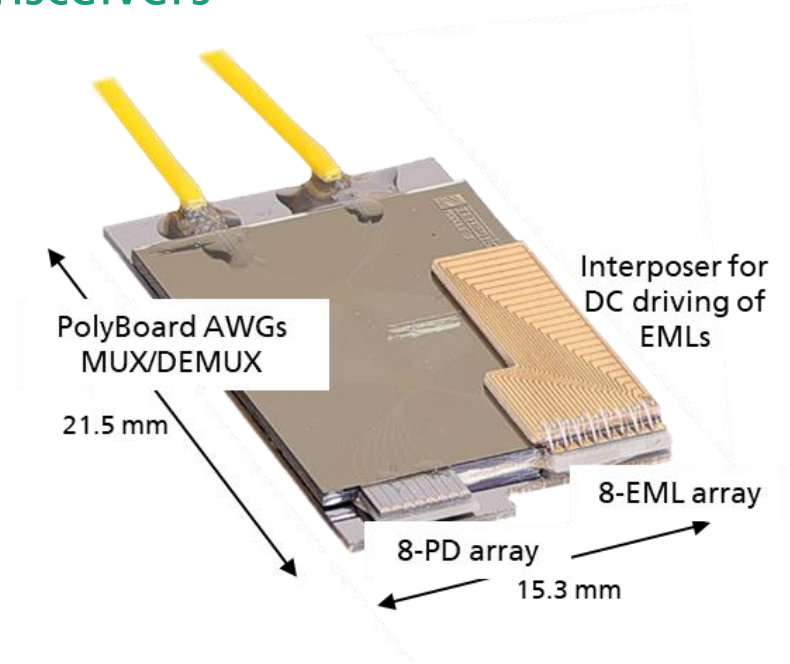
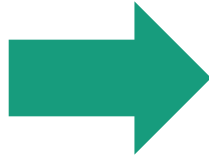
EML Arrays



Waveguide PD Array

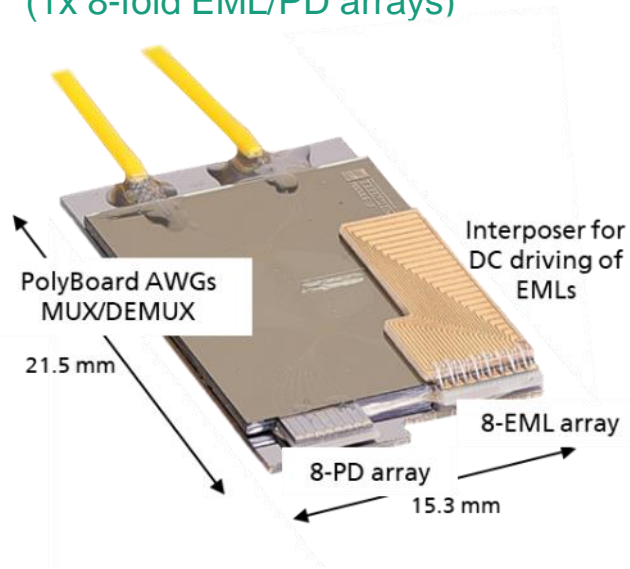


PolyBoard AWGs

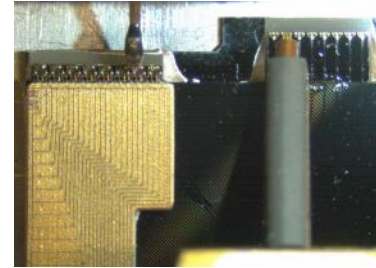


800 Gb/s Hybrid PIC Transceiver

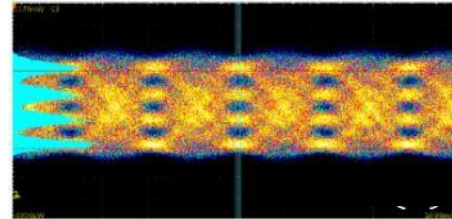
8-Channel
(1x 8-fold EML/PD arrays)



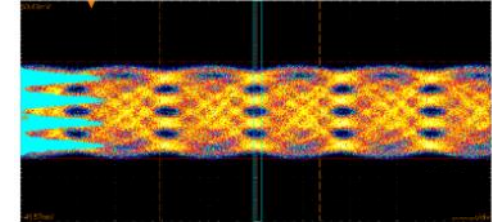
On-PIC testing



Tx: Real-time Eye of 50 Gbaud PAM-4 (B2B)



Rx: Real-time Eye of 50 Gbaud PAM-4 (B2B)

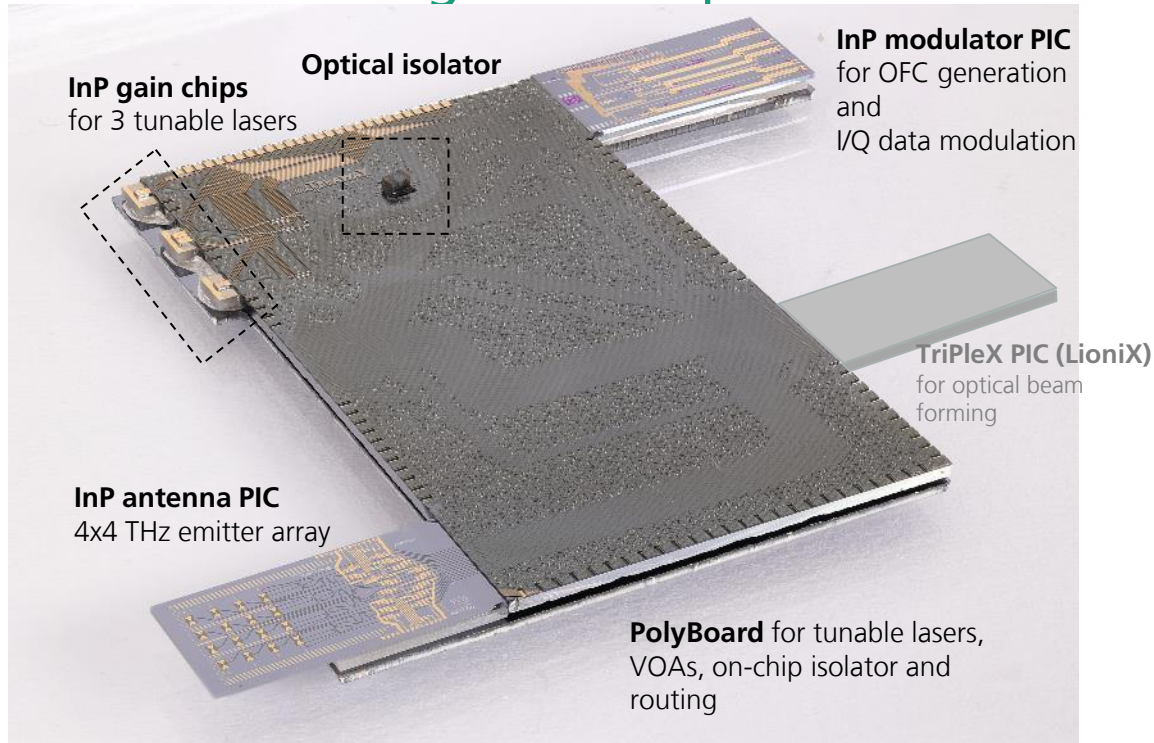


Capability of 800 Gb/s demonstrated

JOCN, 2024

Beam Steerable Tx for Wireless Communications

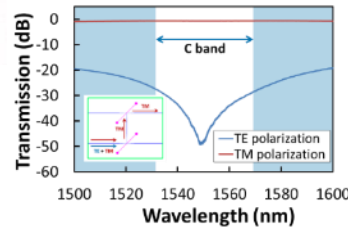
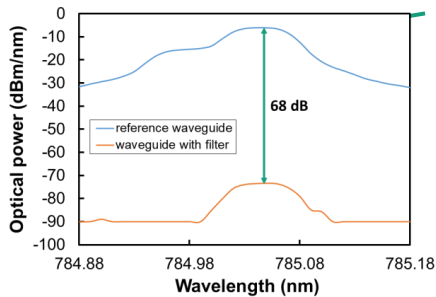
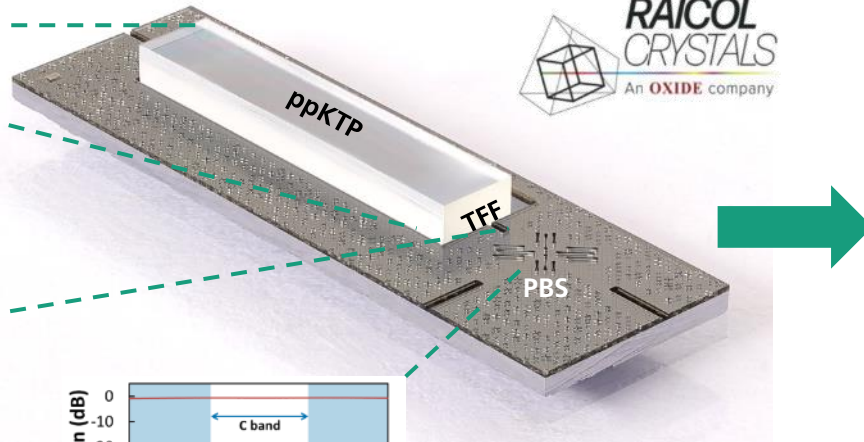
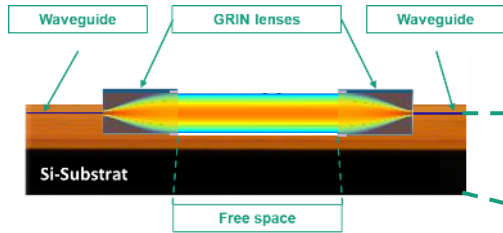
Hybrid PICs Including THz components



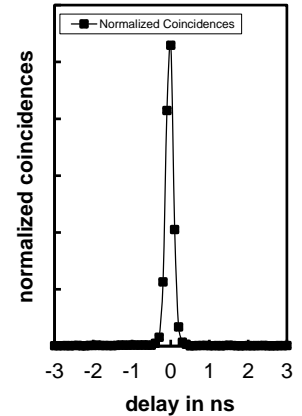
EuMW 2024, Paris

Integrated 1550 nm Photon Pair source

Enabled by micro-optical bench and hybrid integration



Photon pairs
→ bunching



Fraunhofer Heinrich-Hertz-Institut, HHI

**WE PUT SCIENCE
INTO ACTION.**

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